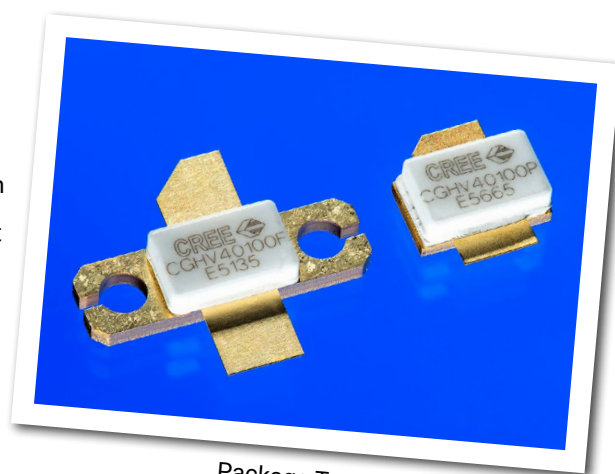


CGHV40100

100 W, DC - 3.0 GHz, 50 V, GaN HEMT

Cree's CGHV40100 is an unmatched, gallium nitride (GaN) high electron mobility transistor (HEMT). The CGHV40100, operating from a 50 volt rail, offers a general purpose, broadband solution to a variety of RF and microwave applications. GaN HEMTs offer high efficiency, high gain and wide bandwidth capabilities making the CGHV40100 ideal for linear and compressed amplifier circuits. The transistor is available in a 2-lead flange and pill package.



Package Types: 440193 & 440206
PN: CGHV40100F & CGHV40100P

Typical Performance Over 500 MHz - 2.5 GHz ($T_c = 25^\circ\text{C}$), 50 V

| Parameter | 500 MHz | 1.0 GHz | 1.5 GHz | 2.0 GHz | 2.5 GHz | Units |
|------------------------------|---------|---------|---------|---------|---------|-------|
| Small Signal Gain | 17.6 | 16.9 | 17.7 | 17.5 | 14.8 | dB |
| Saturated Output Power | 147 | 100 | 141 | 116 | 112 | W |
| Drain Efficiency @ P_{SAT} | 68 | 56 | 58 | 54 | 54 | % |
| Input Return Loss | 6 | 5.1 | 10.5 | 5.5 | 8.8 | dB |

Note:
Measured CW in the CGHV40100F-AMP application circuit.

Features

- Up to 3 GHz Operation
- 100 W Typical Output Power
- 17.5 dB Small Signal Gain at 2.0 GHz
- Application Circuit for 0.5 - 2.5 GHz
- 55 % Efficiency at P_{SAT}
- 50 V Operation



Large Signal Models Available for ADS and MWO

Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

| Parameter | Symbol | Rating | Units | Conditions |
|---|-----------------|-----------|-------|------------|
| Drain-Source Voltage | V_{DS} | 125 | Volts | 25°C |
| Gate-to-Source Voltage | V_{GS} | -10, +2 | Volts | 25°C |
| Storage Temperature | T_{STG} | -65, +150 | °C | |
| Operating Junction Temperature | T_J | 225 | °C | |
| Maximum Forward Gate Current | I_{GMAX} | 20.8 | mA | 25°C |
| Maximum Drain Current ¹ | I_{DMAX} | 8.7 | A | 25°C |
| Soldering Temperature ² | T_S | 245 | °C | |
| Screw Torque | τ | 40 | in-oz | |
| Thermal Resistance, Junction to Case ³ | $R_{\theta JC}$ | 1.62 | °C/W | 85°C |
| Thermal Resistance, Junction to Case ⁴ | $R_{\theta JC}$ | 1.72 | °C/W | 85°C |
| Case Operating Temperature ⁵ | T_C | -40, +150 | °C | |

Note:

¹ Current limit for long term, reliable operation

² Refer to the Application Note on soldering at www.cree.com/RF/Document-Library

³ Measured for the CGHV40100P at $P_{DISS} = 83$ W.

⁴ Measured for the CGHV40100F at $P_{DISS} = 83$ W.

⁵ See also, Power Derating Curve on Page 5.

Electrical Characteristics ($T_C = 25^\circ\text{C}$)

| Characteristics | Symbol | Min. | Typ. | Max. | Units | Conditions |
|--|--------------|------|------|--------|----------|---|
| DC Characteristics¹ | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | -3.8 | -3.0 | -2.3 | V_{DC} | $V_{DS} = 10$ V, $I_D = 20.8$ mA |
| Gate Quiescent Voltage | $V_{GS(Q)}$ | – | -2.7 | – | V_{DC} | $V_{DS} = 50$ V, $I_D = 0.6$ A |
| Saturated Drain Current ² | I_{DS} | 15.6 | 18.7 | – | A | $V_{DS} = 6.0$ V, $V_{GS} = 2.0$ V |
| Drain-Source Breakdown Voltage | V_{BR} | 150 | – | – | V_{DC} | $V_{GS} = -8$ V, $I_D = 20.8$ mA |
| RF Characteristics³ ($T_C = 25^\circ\text{C}$, $F_0 = 2.0$ GHz unless otherwise noted) | | | | | | |
| Small Signal Gain | G_{SS} | – | 17.5 | – | dB | $V_{DD} = 50$ V, $I_{DQ} = 0.6$ A |
| Power Gain | G_P | – | 11.0 | – | dB | $V_{DD} = 50$ V, $I_{DQ} = 0.6$ A, $P_{OUT} = P_{SAT}$ |
| Power Output at Saturation ⁴ | P_{SAT} | – | 116 | – | W | $V_{DD} = 50$ V, $I_{DQ} = 0.6$ A |
| Drain Efficiency | η | – | 54 | – | % | $V_{DD} = 50$ V, $I_{DQ} = 0.6$ A, $P_{OUT} = P_{SAT}$ |
| Output Mismatch Stress | VSWR | – | – | 10 : 1 | Ψ | No damage at all phase angles, $V_{DD} = 50$ V, $I_{DQ} = 0.6$ A, $P_{OUT} = 100$ W CW |
| Dynamic Characteristics⁵ | | | | | | |
| Input Capacitance | C_{GS} | – | 29.3 | – | pF | $V_{DS} = 50$ V, $V_{GS} = -8$ V, $f = 1$ MHz |
| Output Capacitance | C_{DS} | – | 7.3 | – | pF | $V_{DS} = 50$ V, $V_{GS} = -8$ V, $f = 1$ MHz |
| Feedback Capacitance | C_{GD} | – | 0.61 | – | pF | $V_{DS} = 50$ V, $V_{GS} = -8$ V, $f = 1$ MHz |

Notes:

¹ Measured on wafer prior to packaging.

² Scaled from PCM data.

³ Measured in CGHV40100-AMP

⁴ P_{SAT} is defined as $I_G = 0.208$ mA.

⁵ Includes package

CGHV40100 Typical Performance

Figure 1. - Small Signal Gain and Return Losses versus Frequency measured in application circuit CGHV40100-AMP
 $V_{DD} = 50\text{ V}$, $I_{DQ} = 600\text{ mA}$, $T_{case} = 25^{\circ}\text{C}$

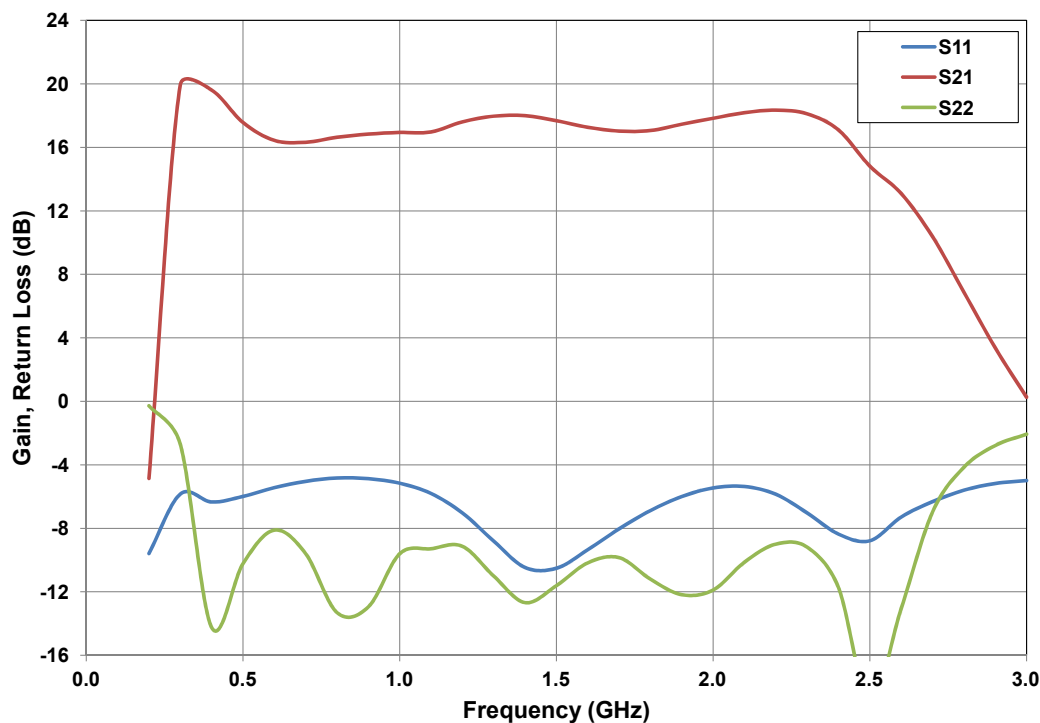
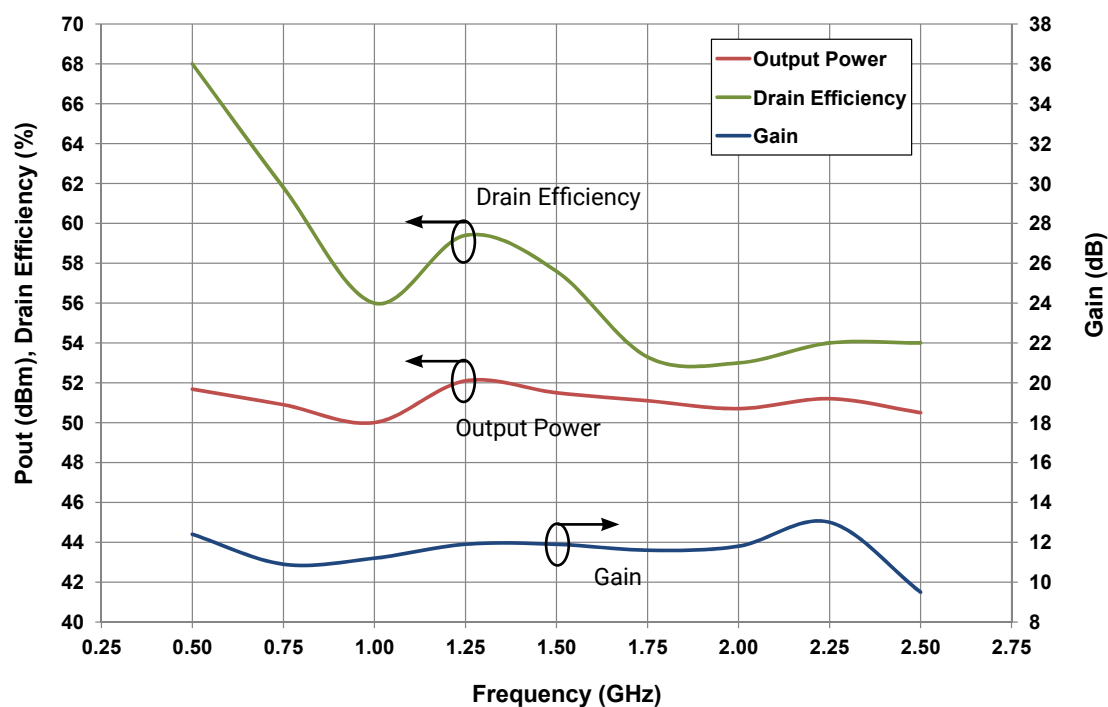


Figure 2. - Output Power and Drain Efficiency vs Frequency
 $V_{DD} = 50\text{ V}$, $I_{DQ} = 600\text{ mA}$



CGHV40100 Typical Performance

Figure 3. - Third Order Intermodulation Distortion vs Average Output Power
 measured in Broadband Amplifier Circuit CGHV40100-AMP
 Spacing = 1 MHz, $V_{DD} = 50\text{ V}$, $I_{DQ} = 600\text{ mA}$, $T_{case} = 25^\circ\text{C}$

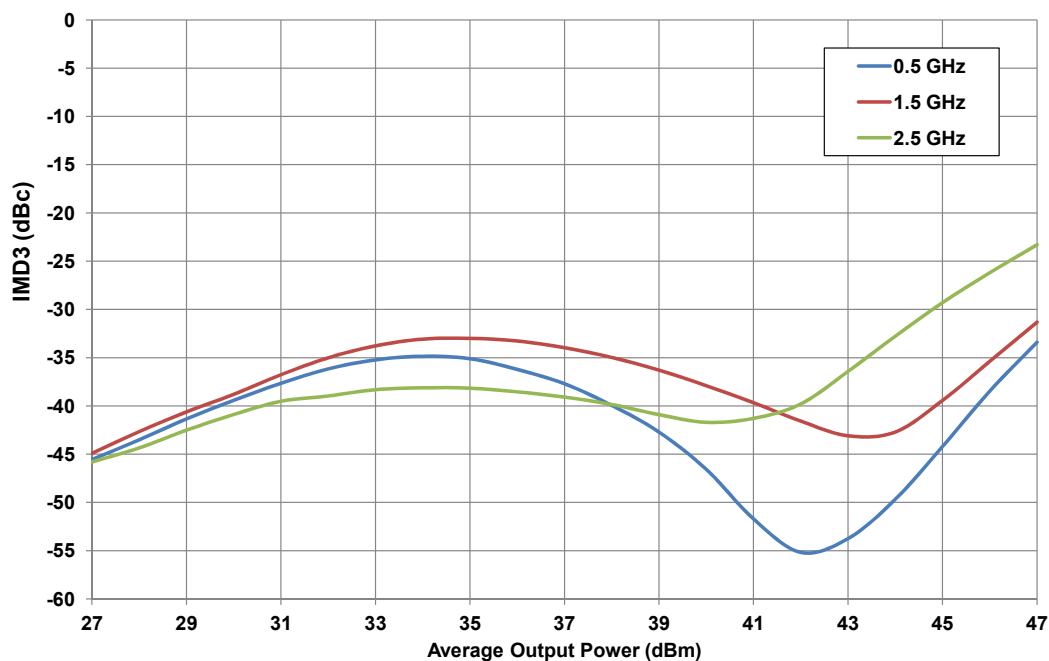
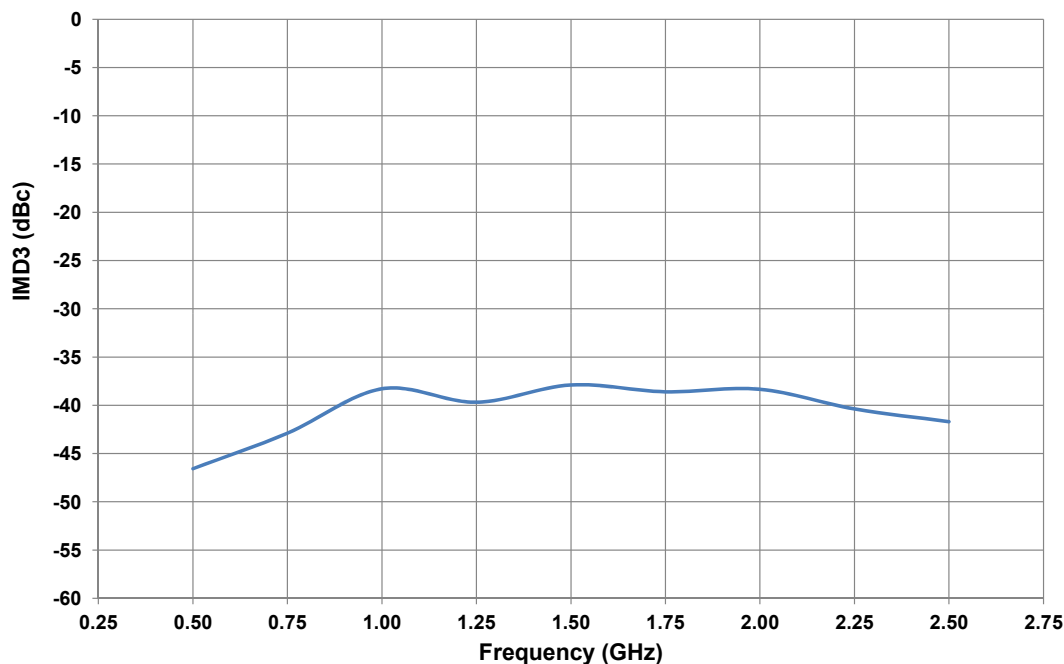
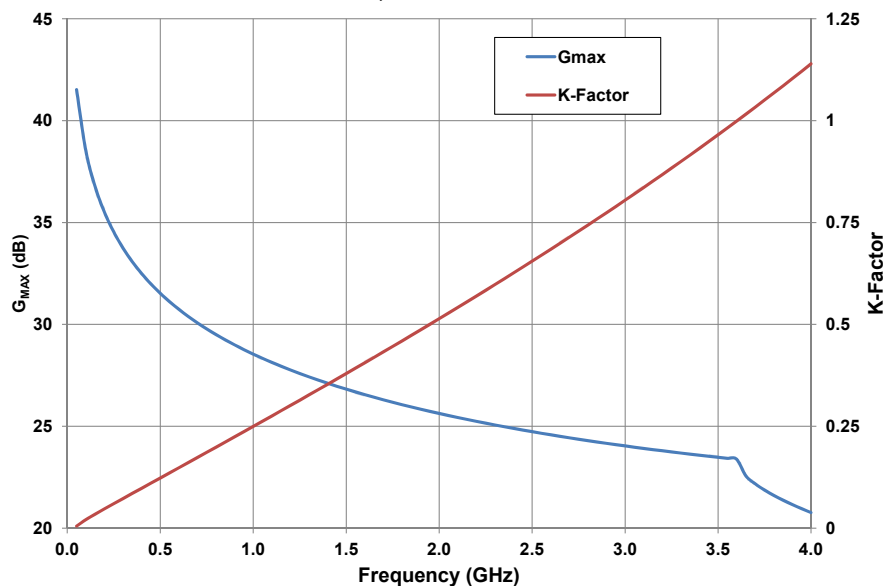


Figure 4. - Third Order Intermodulation Distortion vs Frequency
 measured in Broadband Amplifier Circuit CGHV40100-AMP
 Spacing = 1 MHz, $V_{DD} = 50\text{ V}$, $I_{DQ} = 600\text{ mA}$, $T_{case} = 25^\circ\text{C}$



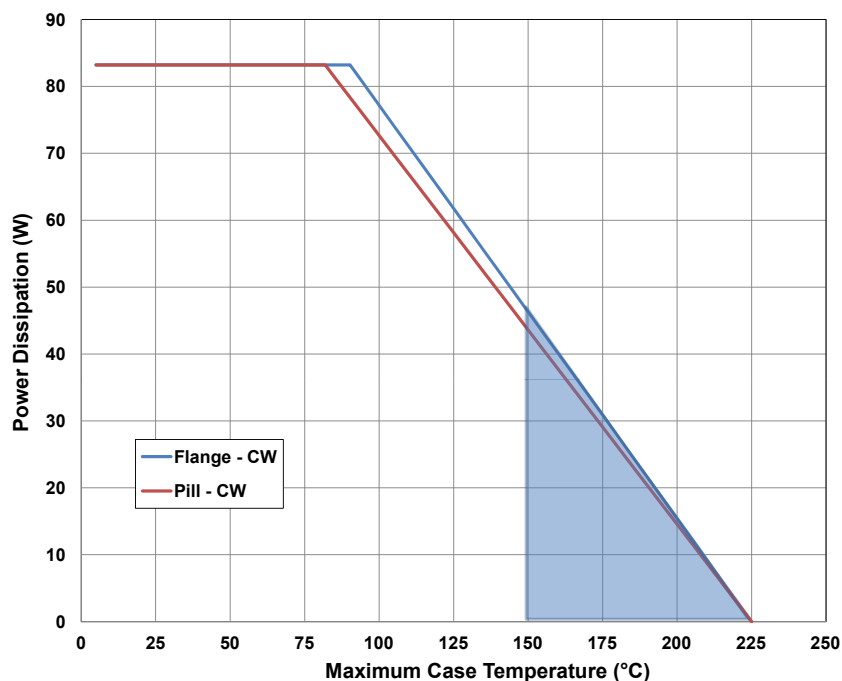
CGHV40100 Typical Performance

Figure 5. - G_{MAX} and K-Factor vs Frequency
 $V_{DD} = 50\text{ V}$, $I_{DQ} = 600\text{ mA}$, $T_{case} = 25^{\circ}\text{C}$



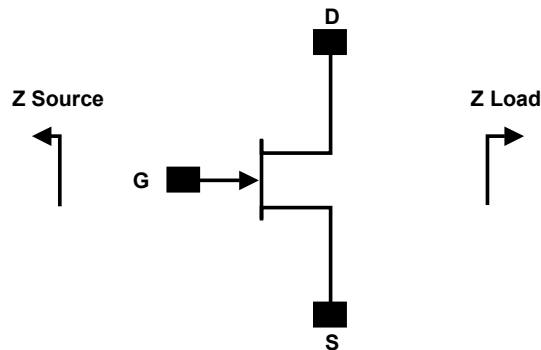
CGHV40100 Power Dissipation De-rating Curve

Figure 6. - Transient Power Dissipation De-Rating Curve



Note 1. Area exceeds Maximum Case Temperature (See Page 2).

Source and Load Impedances



| Frequency (MHz) | Z Source | Z Load |
|-----------------|----------------|-----------------|
| 500 | $0.43 + j5.25$ | $8.83 + j0.85$ |
| 750 | $0.40 + j2.62$ | $10.78 + j2.50$ |
| 1000 | $0.30 + j1.31$ | $9.06 + j4.23$ |
| 1250 | $0.30 + j0.44$ | $7.40 + j3.85$ |
| 1500 | $0.30 - j0.44$ | $6.39 + j3.44$ |
| 1750 | $0.25 - j0.87$ | $4.41 + j3.03$ |
| 2000 | $0.25 - j1.31$ | $3.68 + j2.17$ |
| 2250 | $0.25 - j2.18$ | $3.42 + j2.17$ |
| 2500 | $0.26 - j2.62$ | $2.65 + j1.74$ |

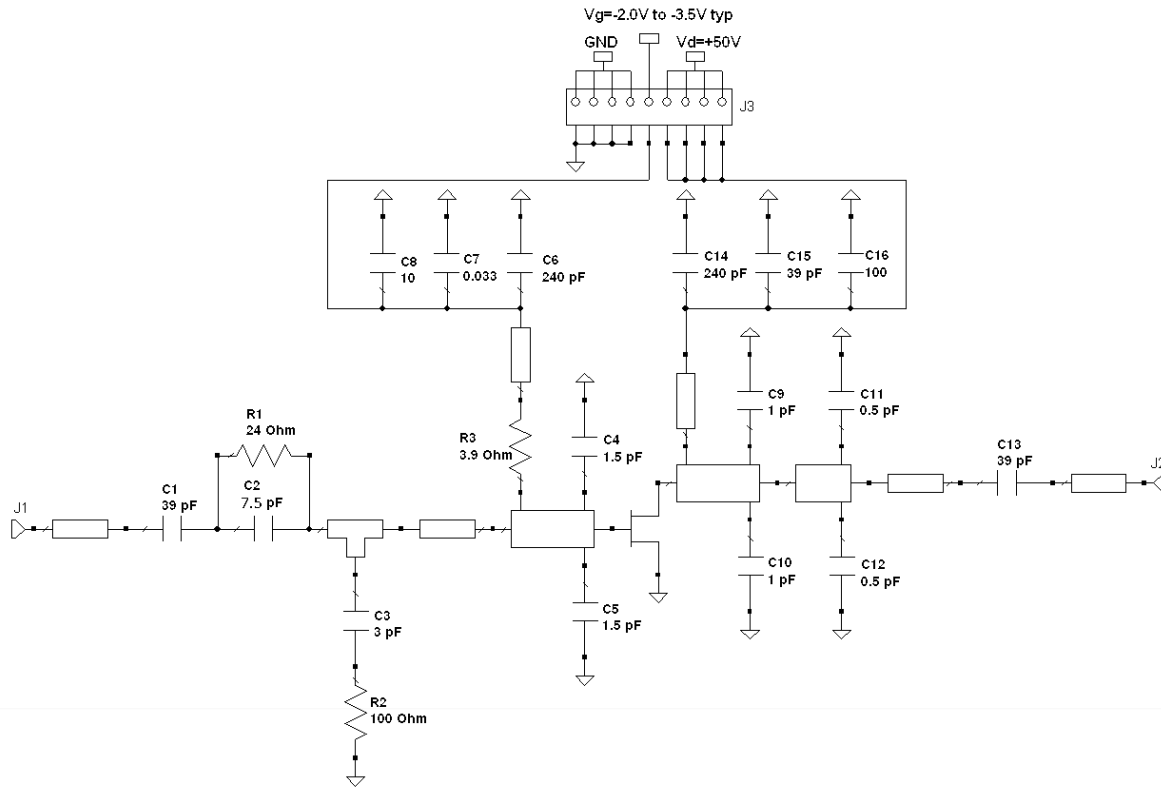
Note 1. $V_{DD} = 50$ V, $I_{DQ} = 600$ mA in the 440193 package.

Note 2. Optimized for power gain, P_{SAT} and PAE.

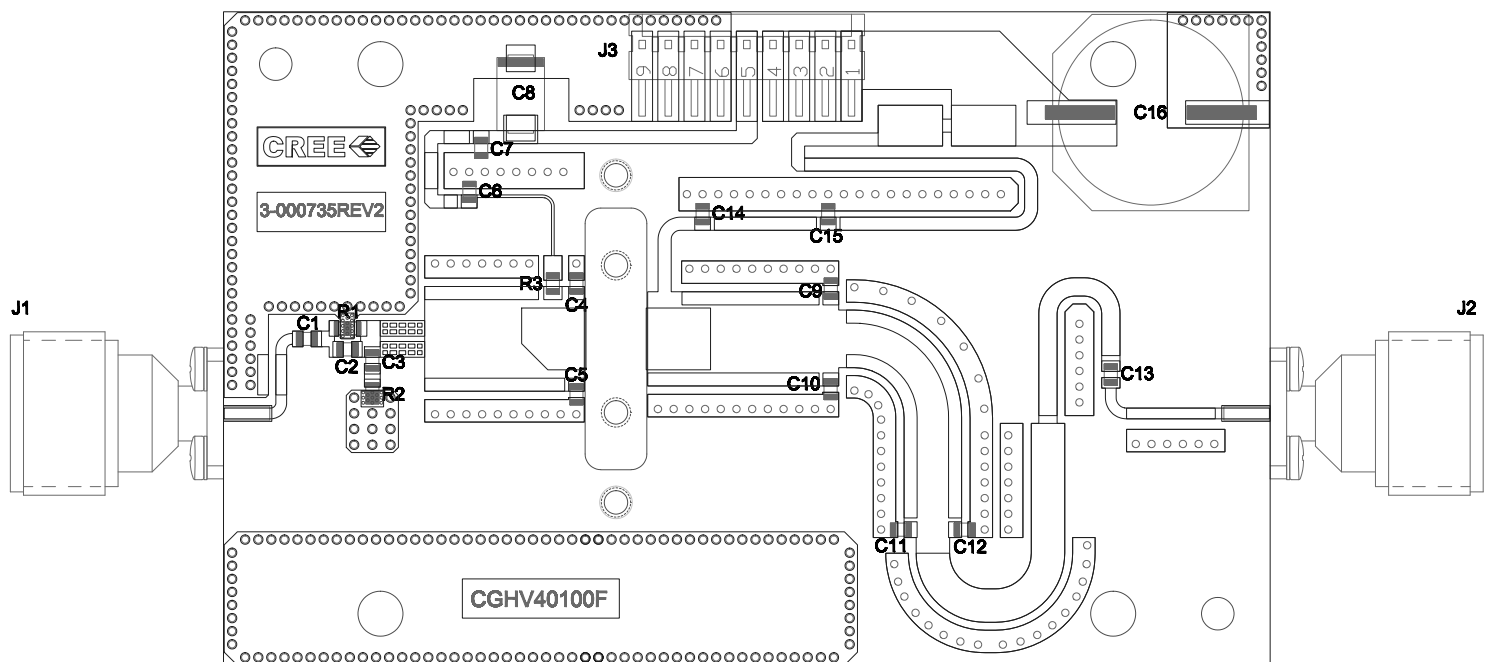
Electrostatic Discharge (ESD) Classifications

| Parameter | Symbol | Class | Test Methodology |
|---------------------|--------|--------------------|---------------------|
| Human Body Model | HBM | 1A (> 250 V) | JEDEC JESD22 A114-D |
| Charge Device Model | CDM | 2 (125 V to 250 V) | JEDEC JESD22 C101-C |

CGHV40100-AMP Application Circuit Schematic



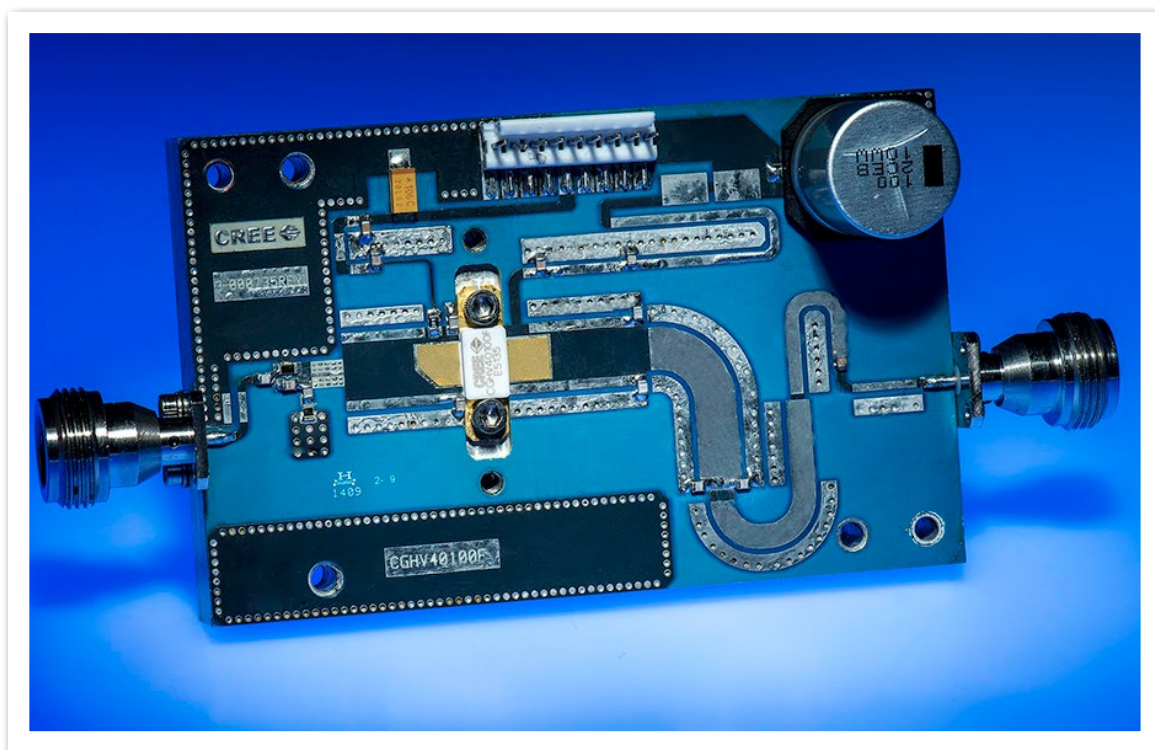
CGHV40100-AMP Application Circuit



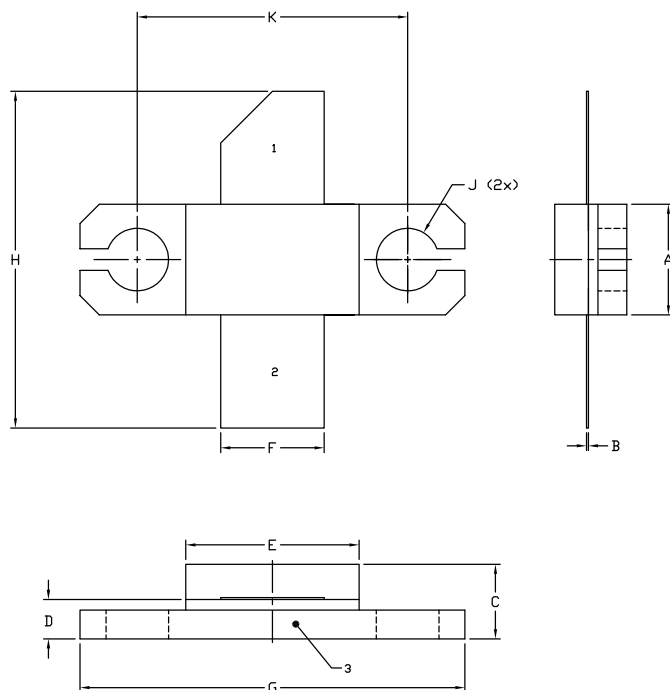
CGHV40100-AMP Application Circuit Bill of Materials

| Designator | Description | Qty |
|--------------|---|-----|
| C1, C13, C15 | CAP, 39 pF, ± 0.1 pF, 250V, 0805, ATC600F | 3 |
| C2 | CAP, 7.5 pF, ± 0.1 pF, 250 V, 0806, ATC600F | 1 |
| C3 | CAP, 3 pF ± 0.1 pF, 250 V, 0805, ATC600F | 1 |
| C4, C5 | CAP, 1.5 pF, ± 0.1 pF, 250 V, 0805, ATC600F | 2 |
| C7 | CAP, 33000 pF, 0805 100V, X7R | 1 |
| C6, C14 | CAP, 240 pF, ± 0.5 pF, 250 V, 0805, ATC600F | 2 |
| C8 | CAP, 10 UF, 16V TANTALUM, 2312 | 1 |
| C9, C10 | CAP, 1 pF, ± 0.1 pF, 250 V, 0805, ATC600F | 2 |
| C11, C12 | CAP, 0.5 pF, ± 0.1 pF, 250 V, 0805, ATC600F | 2 |
| C16 | CAP, 100 UF, 20%, 160 V, ELEC | 1 |
| R1 | RES, 24 OHMS, IMS ND3-1005CS24R0G | 1 |
| R2 | RED, 100 OHMS, IMS ND3-0805EW1000G | 1 |
| R3 | RES, 3.9 OHMS, 0805 | 1 |
| J1, J2 | CONN, SMA, PANEL MOUNT JACK | 2 |
| J3 | HEADER RT>PLZ .1CEN LK 9POS | 1 |
| | BASEPLATE, CGH35120 | 1 |
| | PCB, RO4350B, 2.5" X 4" X 0.020", CGHV40100F | 1 |

CGHV40100-AMP Demonstration Amplifier Circuit



Product Dimensions CGHV40100F (Package Type – 440193)



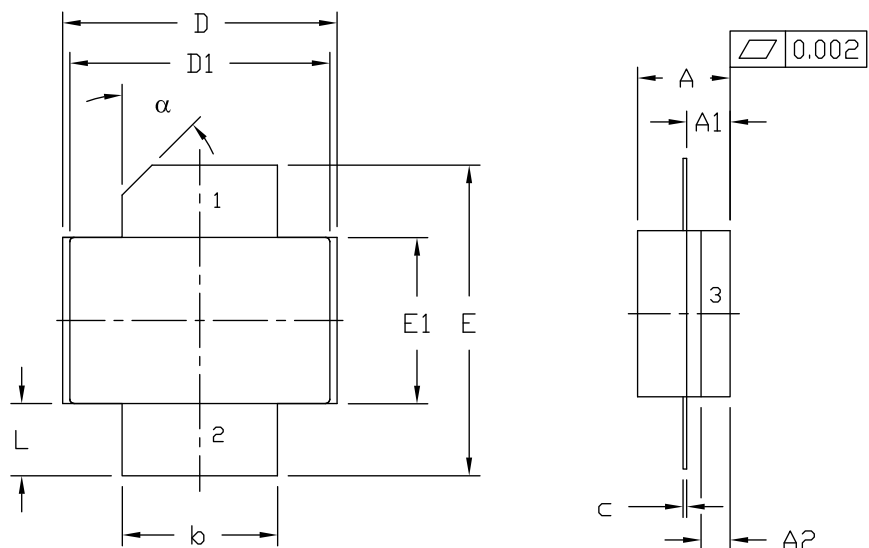
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE Ni/AU.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.225 | 0.235 | 5.72 | 5.97 |
| B | 0.004 | 0.006 | 0.10 | 0.15 |
| C | 0.145 | 0.165 | 3.68 | 4.19 |
| D | 0.077 | 0.087 | 1.96 | 2.21 |
| E | 0.355 | 0.365 | 9.02 | 9.27 |
| F | 0.210 | 0.220 | 5.33 | 5.59 |
| G | 0.795 | 0.805 | 20.19 | 20.45 |
| H | 0.670 | 0.730 | 17.02 | 18.54 |
| J | Ø .130 | | 3.30 | |
| k | 0.562 | | 14.28 | |

PIN 1. GATE
PIN 2. DRAIN
PIN 3. SOURCE

Product Dimensions CGHV40100P (Package Type – 440206)



NOTES:

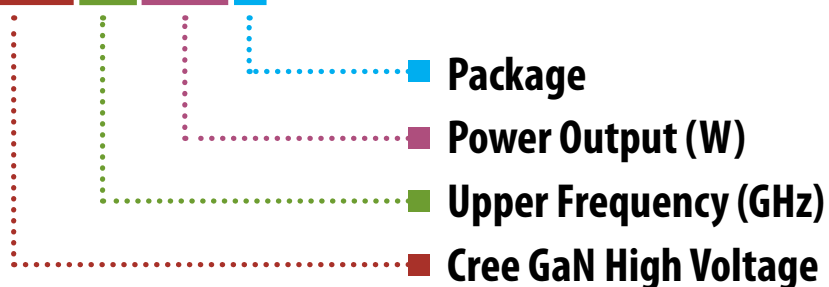
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M – 1994.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.

| DIM | INCHES | | MILLIMETERS | | NOTES |
|-----|---------|-------|-------------|-------|-------|
| | MIN | MAX | MIN | MAX | |
| A | 0.125 | 0.145 | 3.18 | 3.68 | |
| A1 | 0.057 | 0.067 | 1.45 | 1.70 | |
| A2 | 0.035 | 0.045 | 0.89 | 1.14 | |
| b | 0.210 | 0.220 | 5.33 | 5.59 | 2x |
| c | 0.004 | 0.006 | 0.10 | 0.15 | 2x |
| D | 0.375 | 0.385 | 9.53 | 9.78 | |
| D1 | 0.355 | 0.365 | 9.02 | 9.27 | |
| E | 0.400 | 0.460 | 10.16 | 11.68 | |
| E1 | 0.225 | 0.235 | 5.72 | 5.97 | |
| L | 0.085 | 0.115 | 2.16 | 2.92 | 2x |
| α | 45° REF | | 45° REF | | |

PIN 1. GATE
2. DRAIN
3. SOURCE

Part Number System

CGHV40100F



| Parameter | Value | Units |
|------------------------------|--------|-------|
| Upper Frequency ¹ | 4.0 | GHz |
| Power Output | 100 | W |
| Package | Flange | - |

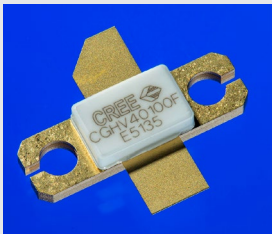
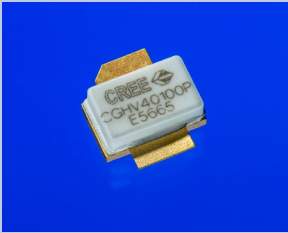
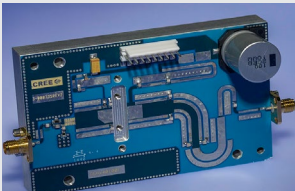
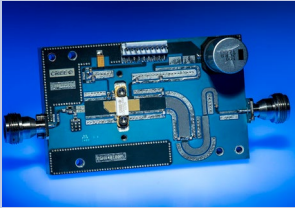
Table 1.

Note¹: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

| Character Code | Code Value |
|----------------|--------------------------------|
| A | 0 |
| B | 1 |
| C | 2 |
| D | 3 |
| E | 4 |
| F | 5 |
| G | 6 |
| H | 7 |
| J | 8 |
| K | 9 |
| Examples: | 1A = 10.0 GHz 2H = 27.0 GHz |

Table 2.

Product Ordering Information

| Order Number | Description | Unit of Measure | Image |
|----------------|--|-----------------|---|
| CGHV40100F | GaN HEMT | Each |  |
| CGHV40100P | GaN HEMT | Each |  |
| CGHV40100-TB | Test board without GaN HEMT | Each |  |
| CGHV40100F-AMP | Test board with GaN HEMT (flanged) installed | Each |  |
| CGHV40100P-AMP | Test board with GaN HEMT(pill) installed | Each | Photo TBD |

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